



JOCHC15B-D8P/S Series

Rev.A.1.0

The products are 15MBd high-speed opto-couplers in a plastic DIP8 package with different lead forming options. The device consists of a 850 nm AlGaAS LED, optically coupled to a very high speed integrated photo-detector logic gate with a strobable output. The output end of the product is a CMOS output, and the product has a strong common mode rejection capability. The coupled parameters are guaranteed over the temperature range of -40°C to +110°C. The products are widely used in communication interface, digital isolation for A/D, D/A conversion, high-voltage power systems, renewable energy inverters, medical imaging and patient monitoring.

High isolation 5000 VRMS

High speed – 15MBd typical

Operating temperature range -40°C to 110°C

REACH & RoHS compliance

HBM: H3A; MM: M4; CDM: C3

CQC approved

VDE approved

UL approved

LED	Output
ON	L
OFF	H

(Temperature=25°C)

Parameter		Symbol	Value	Unit
Input	Forward Current	I _F	50	mA
	Peak Forward Current	I _{FP}	1	A
Reverse Voltage		V _R	6	V

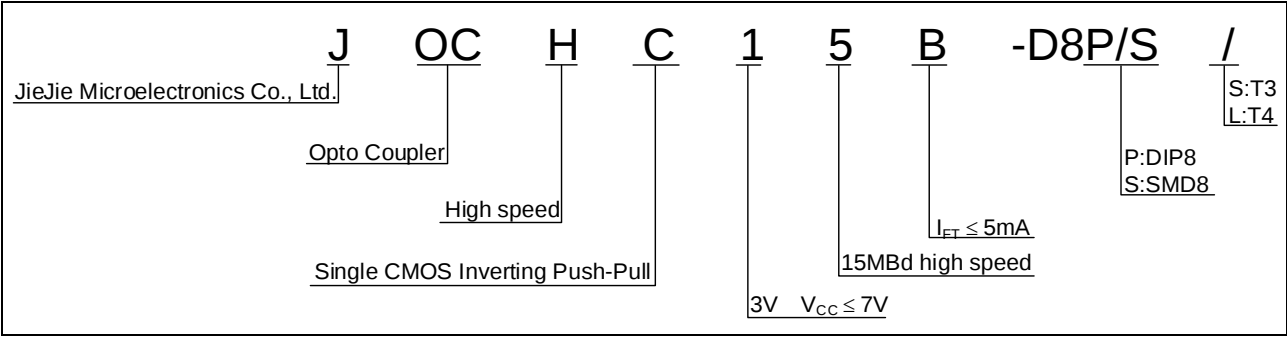


	Input Power Dissipation	P_D	100	mW
Output	Supply Voltage	V_{CC}	7	V
	Output Voltage	V_O	$V_{CC}+0.5$	V
	Output Current	I_O	10	mA
	Output Power Dissipation	P_O	22	mW
Total Power Dissipation		P_{tot}	130	mW
Isolation Voltage		V_{iso}	5000	Vrms
Operating Temperature		T_{opr}	-40~110	
Junction Temperature		T_j	125	
Storage Temperature		T_{stg}	-55~125	
Soldering Temperature		T_{sol}	260	

: 100 μ s pulse, 100Hz frequency

: AC for 1minute, R.H.=40~60%

(Temperature=25°C)



DIP	0 Units/Tube
SMD	1200 Units/Reel

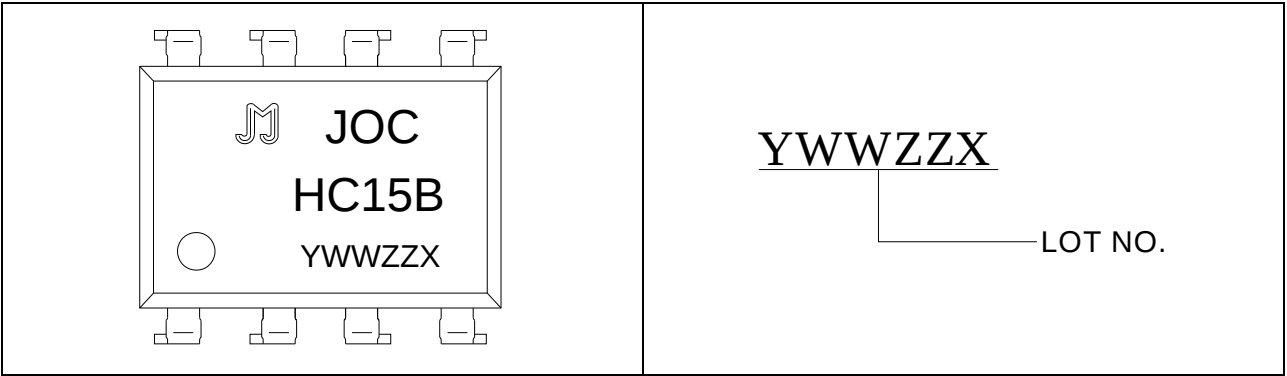


FIG.1: Forward Current vs. Forward Voltage



FIG.2: Max. Allowable LED Forward Current vs. Ambient Temperature

FIG.7: Propagation Delay vs. Ambient Temperature

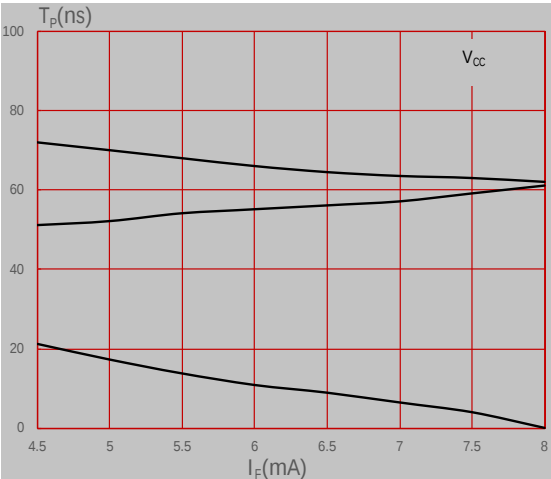
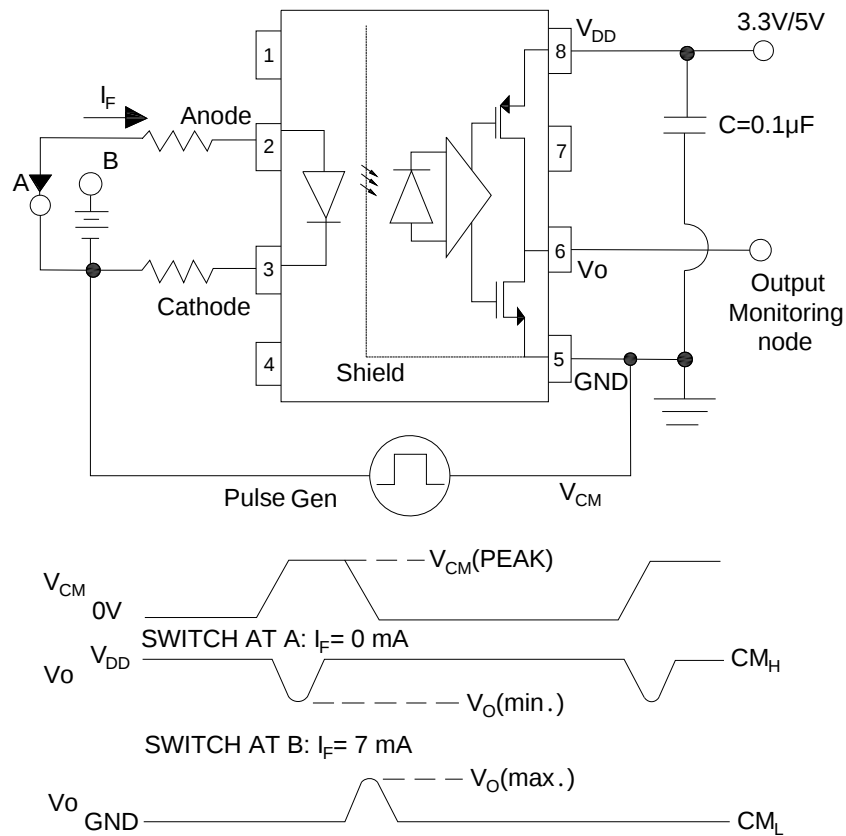


FIG.8: Propagation Delay vs. Ambient Temperature

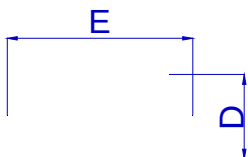
Fig.10: CMTI Test Circuit Recommendations

**Standard DIP Type:**

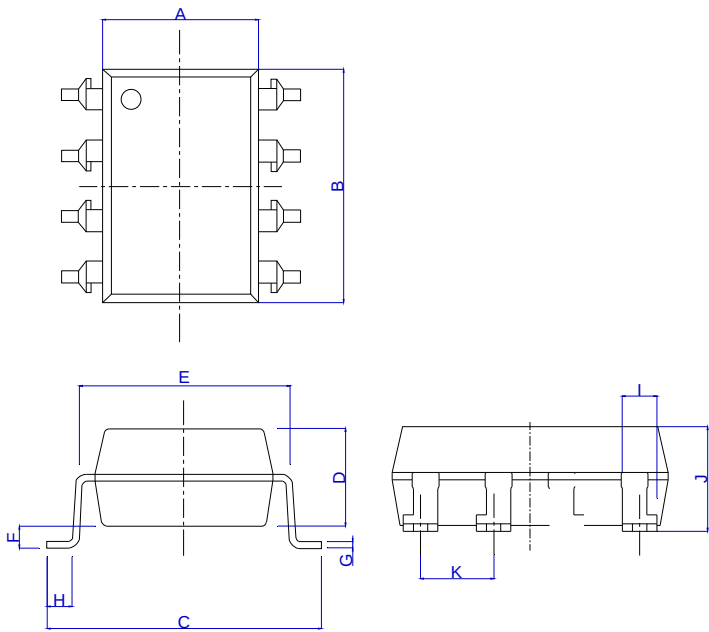
Dimensions

Millimeters

Inches

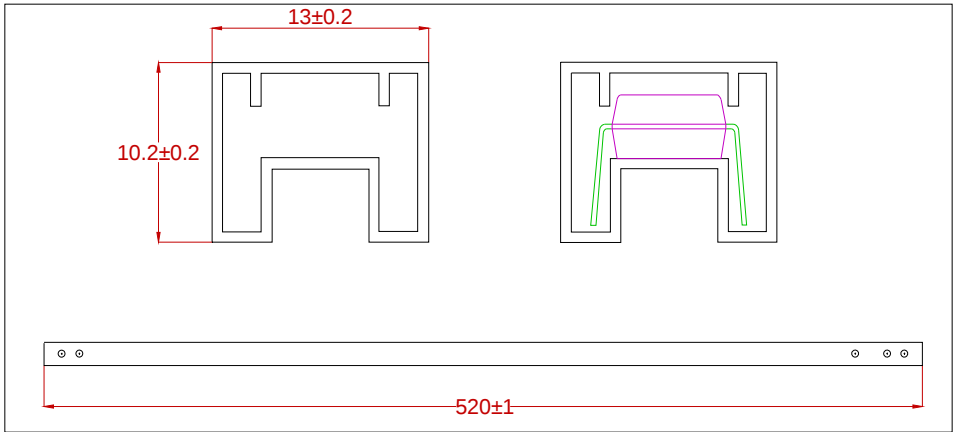


Option SMD Type:

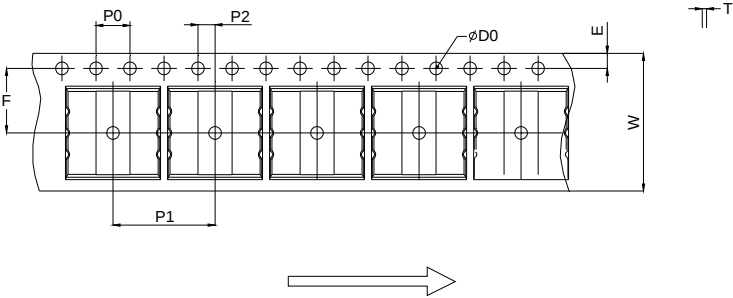


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	9.40		9.80	0.370		0.386
C	9.50		10.50	0.374		0.413
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.05		0.35	0.002		0.014
G	0.16		0.36	0.006		0.014
H	0.60		1.40	0.024		0.055
I	0.90		1.50	0.035		0.059
J	3.30		3.90	0.130		0.154
K	2.29		2.79	0.090		0.110

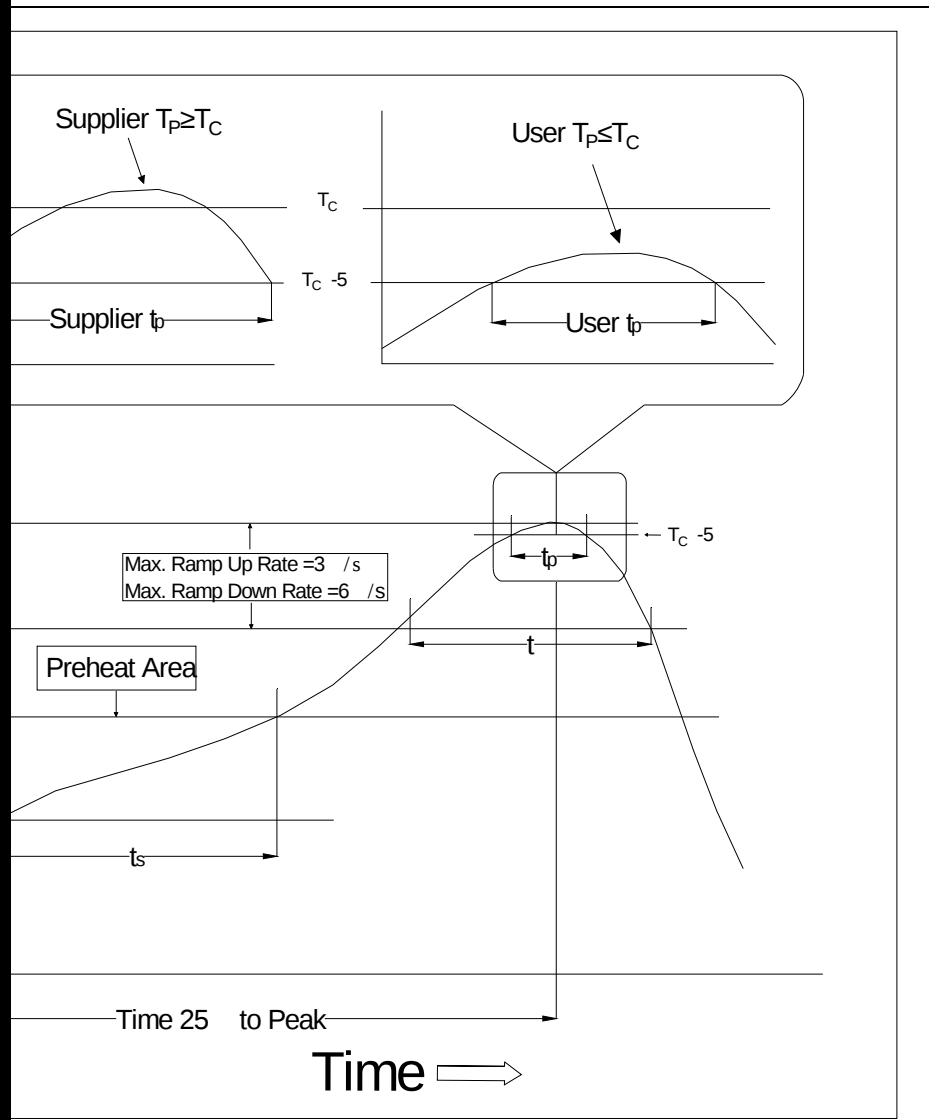
Standard DIP



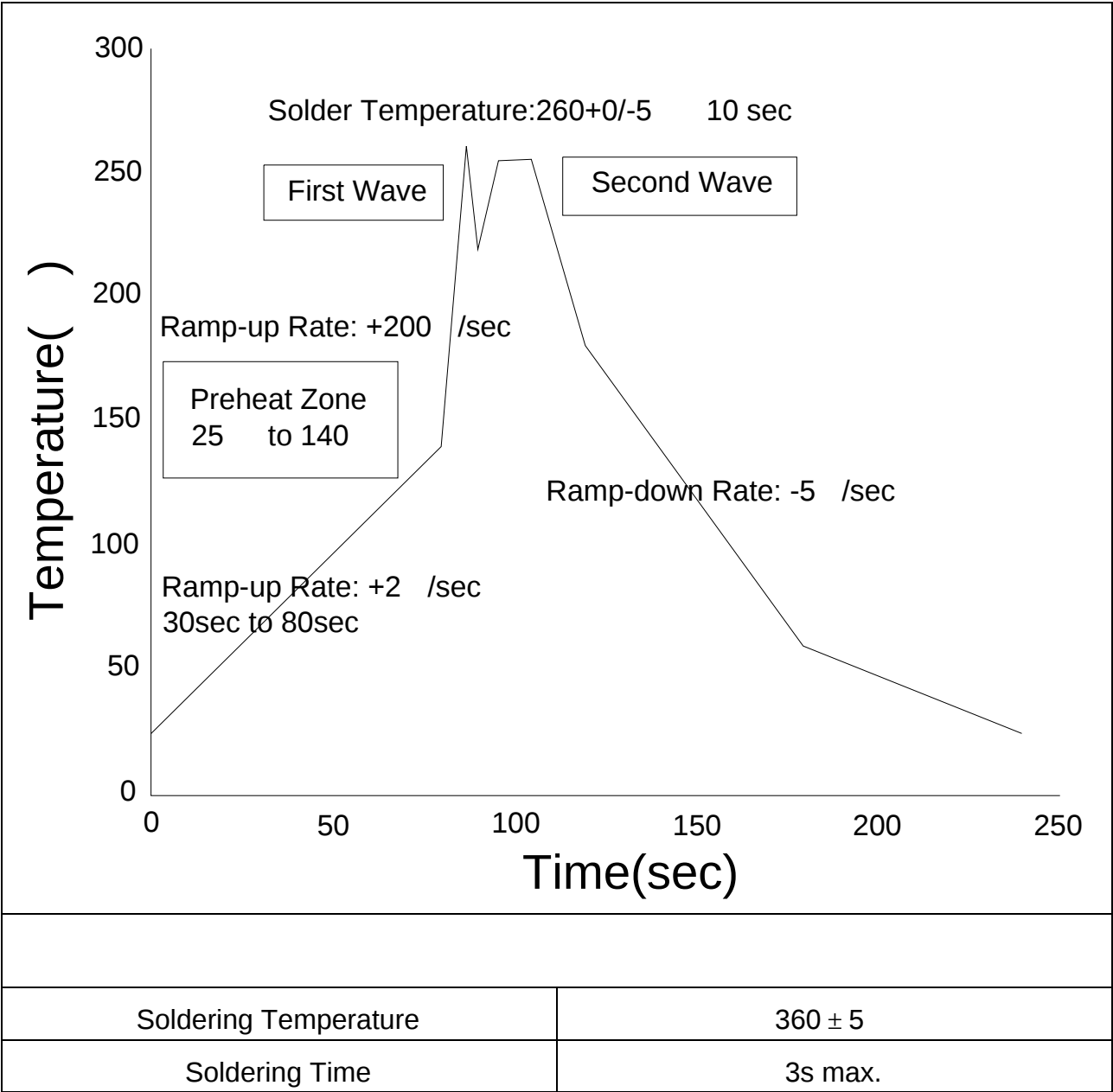
Option S/L



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.90	16.00	16.20	0.626	0.630	0.638



	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
(min)	100	150
(max)	150	200
(smax)	60-120 seconds	60-120 seconds
(P)	3 °/second max.	3 °/second max.
(TL)	183	217
ve (TL)	60-150 seconds	60-150 seconds



Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;
Recommend storage humidity: <60%;
MSL level: MSL 1

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